

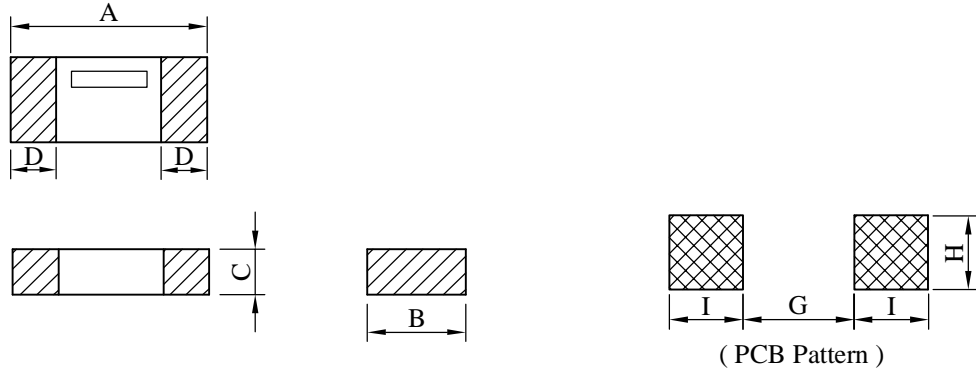
SPECIFICATION FOR APPROVAL

REF : 20101124-C

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PROD. NAME	THIN FILM CHIP INDUCTOR	ABC'S DWG NO.	AL1608□□□□L□-□□□
		ABC'S ITEM NO.	

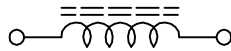
I . CONFIGURATION & DIMENSIONS :



Unit : m/m

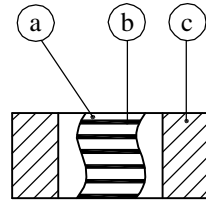
Series	A	B	C	D	G	H	I
AL1608	1.60±0.10	0.80±0.10	0.45±0.10	0.30±0.20	0.9	0.9	0.6

II . SCHEMATIC DIAGRAM :



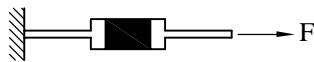
III . MATERIALS :

- a . Body : Ceramic
- b . Internal conductor : Cu
- c . Terminal electrode : Cu/Ni/Sn
- d . Remark : Products comply with RoHS' requirements



IV . GENERAL SPECIFICATION :

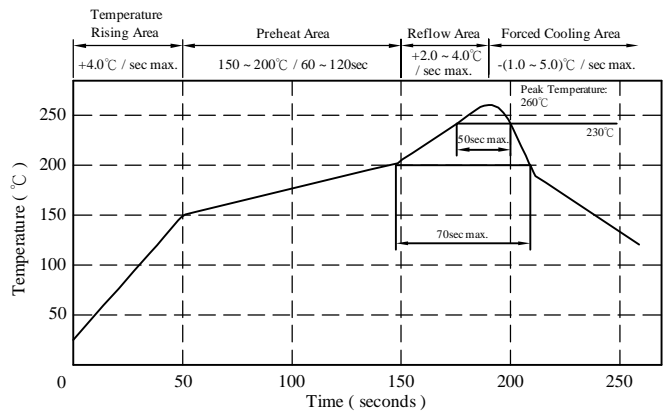
- a . Storage temp. : -40°C ---- +105°C
- b . Operating temp. : -55°C ---- +125°C
- c . Terminal strength :



Type	F (kgf)	Time (sec)
AL1608	0.5	30±5

- d . Solderability : **Preheat : 150±25°C for 60 seconds**
 Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent
 Solder temp. : 260±5°C
 Flux : Rosin
 Dip time : 4±1 seconds

Peak Temp : 260°C max.
 Max time above 230°C : 50sec max.
 Max time above 200°C : 70sec max.



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V . ELECTRICAL CHARACTERISITCS :

DWG No.	Inductance (nH)	Q min	Test Freq. (MHz)	SRF (GHz) min	DC Resistance (Ω) max	Rated Current (mA) max
AL16081N0DL□-□□□	1.0±0.3	15	300	13.0	0.35	800
AL16081N2DL□-□□□	1.2±0.3	15	300	13.0	0.35	800
AL16081N5DL□-□□□	1.5±0.3	15	300	10.0	0.35	800
AL16081N8DL□-□□□	1.8±0.3	15	300	10.0	0.35	300
AL16082N2DL□-□□□	2.2±0.3	15	300	8.0	0.35	300
AL16082N7DL□-□□□	2.7±0.3	15	300	6.0	0.45	300
AL16083N3DL□-□□□	3.3±0.3	15	300	6.0	0.45	300
AL16083N9DL□-□□□	3.9±0.3	15	300	6.0	0.45	300
AL16084N7DL□-□□□	4.7±0.3	15	300	5.0	0.55	300
AL16085N6DL□-□□□	5.6±0.3	15	300	5.0	0.65	300
AL16086N8DL□-□□□	6.8±0.3	15	300	5.0	0.75	300
AL16088N2DL□-□□□	8.2±0.3	15	300	4.0	0.95	300
AL160810N□L□-□□□	10.0±5 %	15	300	4.0	0.95	300
AL160812N□L□-□□□	12.0±5 %	15	300	3.0	1.05	300
AL160815N□L□-□□□	15.0±5 %	15	300	3.0	1.35	300
AL160818N□L□-□□□	18.0±5 %	15	300	2.0	1.65	300
AL160822N□L□-□□□	22.0±5 %	15	300	2.0	1.95	250
AL160827N□L□-□□□	27.0±5 %	15	300	2.0	2.35	250
AL160833N□L□-□□□	33.0±5 %	15	300	1.5	2.75	250
AL160839N□L□-□□□	39.0±5 %	15	300	1.5	3.00	200
AL160847N□L□-□□□	47.0±5 %	15	300	1.5	3.00	200
AL160856N□L□-□□□	56.0±5 %	15	300	1.0	5.00	150
AL160868N□L□-□□□	68.0±5 %	15	300	1.0	5.00	150
AL1608R10□L□-□□□	100.0±5 %	15	300	1.0	7.50	100

1). □ : Packaging Information... A: Bulk B: Taping Reel

2)."- □□□":Reference code

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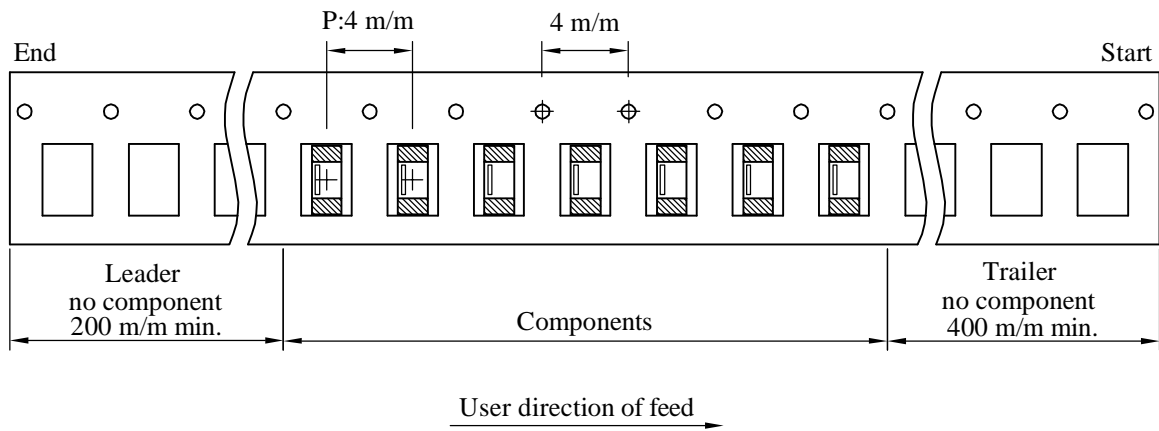
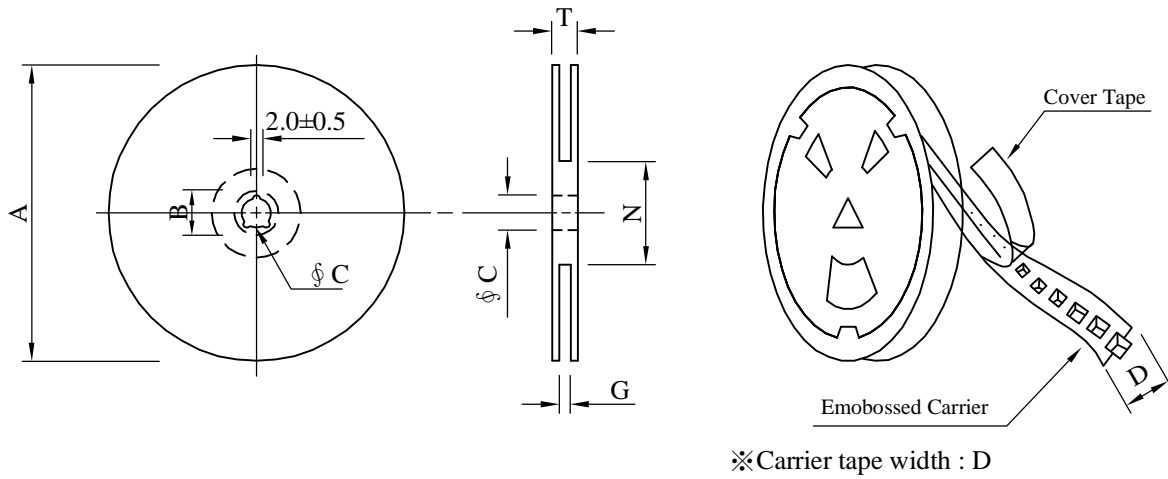
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VI . PACKAGING INFORMATION :

(1) Configuration



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
AL1608	5,000	90	07 - 08	250,000	7.0	41 x 39 x 22

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VIII . RELIABILITY TEST :

Test item	Specification	Test condition						
Solderability	More than 95% of the terminal electrode shall be covered With fresh solder.	Preheat : 155°C / 4 hours. Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent Solder temp. : 235±5°C Flux : Rosin Dip time : 5±0.5 seconds						
Thermal shock test (Temp. cycle)	Electrical oharacteristics shall not change more than ±20%	<table style="width: 100%; border: none;"> <tr> <td style="text-align: center; border: none;">Room temp. 15 minutes</td> <td style="text-align: center; border: none;">→</td> <td style="text-align: center; border: none;">-55 °C 30 minutes</td> </tr> <tr> <td style="text-align: center; border: none;">Room temp. 15 minutes</td> <td style="text-align: center; border: none;">→</td> <td style="text-align: center; border: none;">+125 °C 30 minutes</td> </tr> </table> <p>Total : 50 cycles</p>	Room temp. 15 minutes	→	-55 °C 30 minutes	Room temp. 15 minutes	→	+125 °C 30 minutes
Room temp. 15 minutes	→	-55 °C 30 minutes						
Room temp. 15 minutes	→	+125 °C 30 minutes						
Humidity Test		Temperature : 40±2°C Humidity : 90±5% Time : 1000 hours						
High temp. Resistance test		Temperature : 125±5°C Applied current : Per spec. Time : 96 hours						

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